



N-Channel 80 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}$ (Ω) Max.	I _D (A) ^a	Q _g (Typ.)		
	0.093 at V _{GS} = 10 V	4.6			
80	0.108 at V _{GS} = 6 V	4.3	2.6		
	0.126 at V _{GS} = 4.5 V	4			

FEATURES

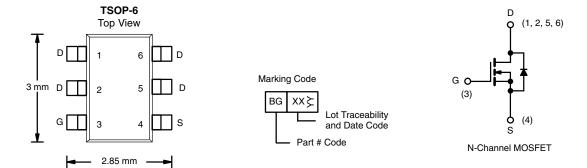
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



HALOGEN FREE

APPLICATIONS

- Load Switch for Portable Applications
- LED Backlight Switch
- DC/DC Converter
- **Boost Converter**



Ordering Information: Si3476DV-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATING	S (T _A = 25 °C, un	less otherwi	se noted)	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	80	V	
Gate-Source Voltage		V_{GS}	± 20	7 v
	T _C = 25 °C		4.6	
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	1_	3.7	
Continuous Diam Curient (1) = 130 °C)	T _A = 25 °C	l _D	3.5 ^{b,c}	Α
	T _A = 70 °C		2.8 ^{b,c}	
Pulsed Drain Current (t = 100 μs)	•	I _{DM}	18	
Continuous Source-Drain Diode Current	T _C = 25 °C	I-	3	A
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	1.7 ^{b,c}	7 ^
	T _C = 25 °C		3.6	
Maximum Payer Dissination	T _C = 70 °C	P _D	2.3	w
Maximum Power Dissipation	T _A = 25 °C	T	2 ^{b,c}	vv
	T _A = 70 °C		1.3 ^{b,c}	7
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b,d}	t ≤ 5 s	R _{thJA}	50	62.5	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	28	35	- 'C/VV	

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 110 °C/W.

Document Number: 62884 S13-1818-Rev. A, 12-Aug-13 For technical questions, contact: pmostechsupport@vishav.com

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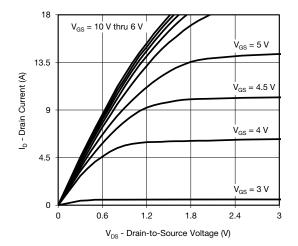
SPECIFICATIONS ($T_J = 25$ °C)	C, unless oth	erwise noted)					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	80			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		36		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 _D = 230 kg (- 4.8			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	Inco	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α	
		V _{GS} = 10 V, I _D = 3.5 A		0.077	0.093		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 6 \text{ V}, I_D = 3.2 \text{ A}$		0.090	0.108	Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$		0.105	0.126	1	
Forward Transconductance	9 _{fs}	V _{DS} = 15 V, I _D = 3.5 A		7		S	
Dynamic ^b			L		l	L	
Input Capacitance	C _{iss}			195			
Output Capacitance	C _{oss}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		116		pF	
Reverse Transfer Capacitance	C _{rss}			16			
·	Q _g	V _{DS} = 40 V, V _{GS} = 10 V, I _D = 3.5 A		4.9	7.5		
Total Gate Charge		20 00 2		2.6	5		
Gate-Source Charge	Q _{gs}	$V_{DS} = 40 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.5 \text{ A}$		0.8		nC	
Gate-Drain Charge	Q _{gd}			1.3			
Gate Resistance	R _g	f = 1 MHz	0.82	4.2	8.2	Ω	
Turn-On Delay Time	t _{d(on)}			8	16		
Rise Time	t _r	$V_{DD} = 40 \text{ V, R}_{1} = 14.3 \Omega$		4	8	ns	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 2.8 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		14	21		
Fall Time	t _f			3	6		
Turn-On Delay Time	t _{d(on)}			26	40		
Rise Time	t _r	$V_{DD} = 40 \text{ V}, R_{I} = 14.3 \Omega$		50	75		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 2.8 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		12	20		
Fall Time	t _f			15	23		
Drain-Source Body Diode Characteris	tics			<u> </u>	1	<u> </u>	
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			3		
Pulse Diode Forward Current (t = 100 μs)	I _{SM}				18	Α	
Body Diode Voltage	V _{SD}	I _S = 2.8 A		0.85	1.2	V	
Body Diode Reverse Recovery Charge	Q _{rr}			13	20	nC	
Body Diode Reverse Recovery Time	t _{rr}	1 004 41/15 4004/		20	30		
Reverse Recovery Fall Time	t _a	$I_F = 2.8 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		10.5		ns	
Reverse Recovery Rise Time	t _b			9.5		-	

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

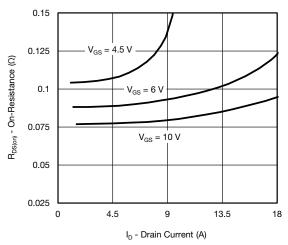
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



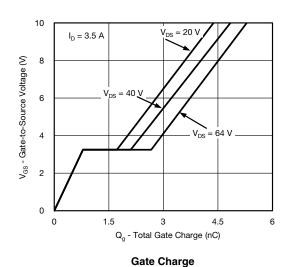
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

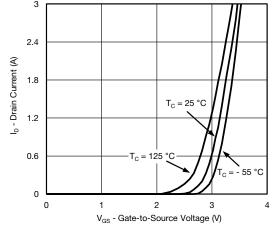


Output Characteristics

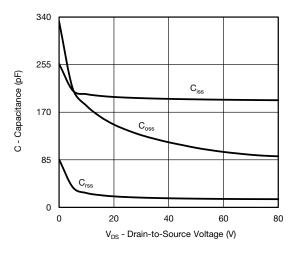


On-Resistance vs. Drain Current

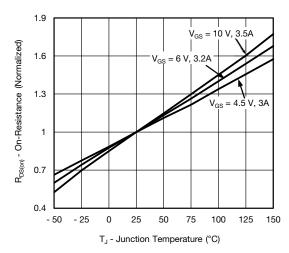




Transfer Characteristics Curves vs. Temp.



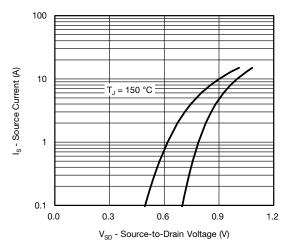
Capacitance



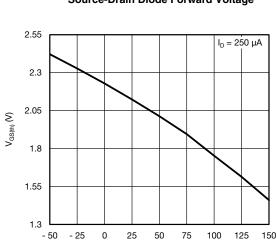
On-Resistance vs. Junction Temperature

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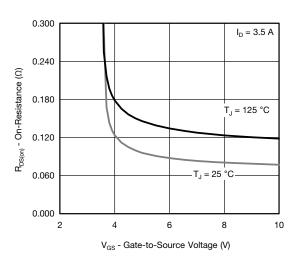
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



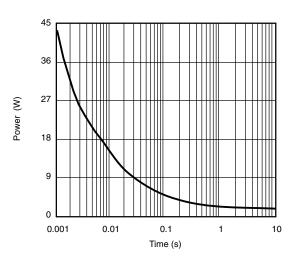
Source-Drain Diode Forward Voltage



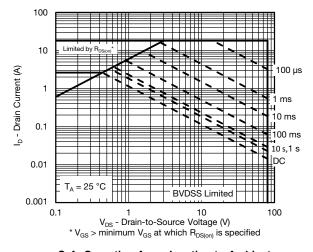
T_J - Temperature (°C) **Threshold Voltage**



 $R_{DS(on)}$ vs. V_{GS} vs. Temperature



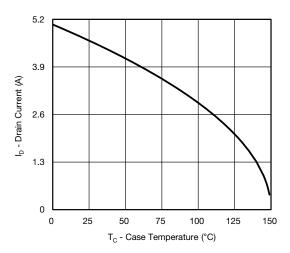
Single Pulse Power (Junction-to-Ambient)



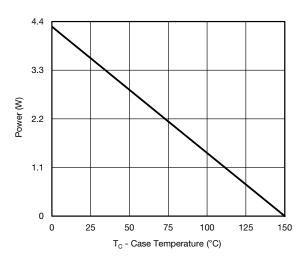
Safe Operating Area, Junction-to-Ambient



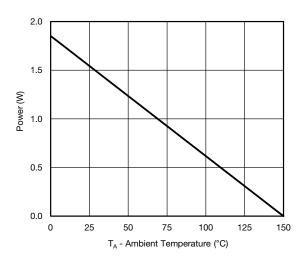
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Current Derating*





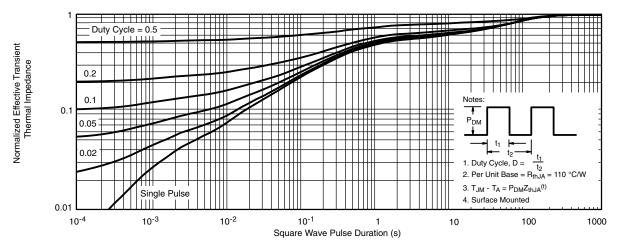


Power Derating, Junction-to-Ambient

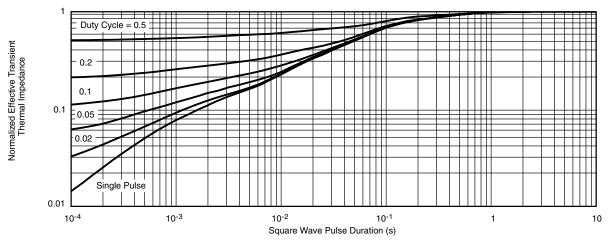
 $^{^*}$ The power dissipation P_D is based on $T_{J(max.)}$ = 150 $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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TSOP: 5/6-LEAD

JEDEC Part Number: MO-193C





5-LEAD TSOP







	MIL	LIMETER	RS	INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.008		
D	2.95	3.05	3.10	0.116 0.120		0.122	
E	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е		0.95 BSC		0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071 0.075 0.			
L	0.32	-	0.50	0.012	-	0.020	
L ₁	0.60 Ref			0.024 Ref			
L ₂	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ1	7° Nom			7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

DWG: 5540

Document Number: 71200 18-Dec-06



Recommended Land Pattern For TSOP-5L / TSOP-6L



Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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